

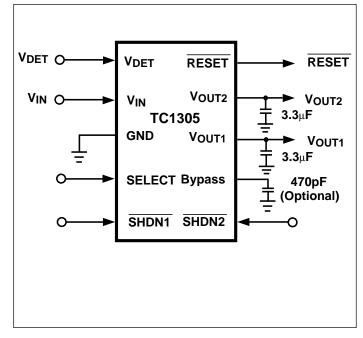
# Dual 150mA CMOS LDO With SelectMode<sup>™</sup> , Shutdown and Independent RESET Output

## **FEATURES**

- Extremely Low Supply Current for Longer Battery Life!
- SelectMode<sup>TM</sup>: Selectable Output Voltages for High Design Flexibility
- Very Low Dropout Voltage
- 10µsec (Typ.) Wake Up Time from SHDN
- Guaranteed 150mA Output Current
- High Output Voltage Accuracy
- Power-Saving Shutdown Mode
- RESET Output Can Be Used as a Low Battery Detector or Processor Reset Generator
- Over-Current and Over-Temperature Protection
- Space-Saving 10-Pin MSOP Package

## **APPLICATIONS**

- Battery Operated Systems
- Portable Computers
- Medical Instruments
- Instrumentation
- Cellular / PHS Phones
- Linear Post-Regulator for SMPS
- Pagers



#### **TYPICAL APPLICATION**

## GENERAL DESCRIPTION

The TC1305 combines two CMOS Low Dropout Regulators and a Microprocessor Monitor in a space-saving 10-Pin MSOP package. Designed specifically for battery-operated systems, the device's CMOS construction eliminates wasted ground current, significantly extending battery life. Total supply current is typically 120µA at full load, 20 to 60 times lower than in bipolar regulators!

The TC1305 features selectable output voltages for higher design flexibility. The tri-state SELECT pin allows the user to select  $V_{OUT1}$  and  $V_{OUT2}$  from 3 different values (2.5V, 2.8V and 3.0V).

An active low  $\overrightarrow{RESET}$  is asserted when the detected voltage (V<sub>DET</sub>) falls below the 2.63V reset voltage threshold. The RESET output remains low for 300msec (typical) after V<sub>DET</sub> rises above the reset threshold. When the shutdown controls (SHDN1 and SHDN2) are low, the regulator output voltages fall to zero, RESET output remains valid and supply current is reduced to 20µA (typ.).

Other key features for the device include ultra low-noise operation, fast response to step changes in load, and very low dropout voltage (typically 240mV at full load). The device also incorporates both over-temperature and over-current protection. Each regulator is stable with an output capacitor of only 1 $\mu$ F and has a maximum output current of 150mA. The 1305 is featured in a 10-pin MSOP package with selective output voltages.

# **ORDERING INFORMATION**

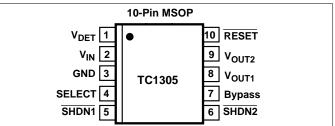
Part Number	Package	Junction Temp. Range	
TC1305R-DVUN	10-Pin MSOP	– 40°C to +125°C	
NOTE: The "R" denotes the suffix for the 2.63V V <sub>DET</sub> threshold			

**Available Output Voltages:** 

D indicates  $V_{OUT1} = V_{OUT2} = 2.5, 2.8, 3.0$  (selectable)

Other output voltages are available. Please contact Microchip Technology Inc. for details.

## PIN CONFIGURATION



# TC1305

## **ABSOLUTE MAXIMUM RATINGS\***

Input Voltage	6.5V
Output Voltage	
Power Dissipation	Internally Limited (Note 7)
Operating Temperature	$-40^{\circ}C < T_{J} < 125^{\circ}C$
Storage Temperature	– 65°C to +150°C

Maximum Voltage On Any Pin ......  $V_{IN}$  + 0.3V to - 0.3V Lead Temperature (Soldering, 10 Sec.).....+260°C

\*Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**ELECTRICAL CHARACTERISTICS:**  $V_{IN} = V_R + 1V$ ,  $I_L = 100\mu A$ ,  $C_L = 3.3\mu F$ ,  $\overline{SHDN1} > V_{IH}$ ,  $\overline{SHDN2} > V_{IH}$ ,  $T_A = 25^{\circ}C$ , unless otherwise noted. **Boldface** type specifications apply for junction temperatures of  $-40^{\circ}C$  to  $+125^{\circ}C$ .

Symbol	Parameter	Test Conditions	Min	Тур —	Max 6.0	Units V
V <sub>IN</sub>	Input Operating Voltage	Note 1	2.7			
IOUTMAX	Maximum Output Current		150			mA
Vout	Output Voltage (VOUT1 and VOUT2	2) Note 2	V <sub>R</sub> – 2.5%	V <sub>R</sub> ±0.5%	V <sub>R</sub> + 2.5%	V
TCV <sub>OUT</sub>	V <sub>OUT</sub> Temperature Coefficient	Note 3	_	20 <b>40</b>	_	ppm/°C
$\Delta V_{OUT} / \Delta V_{IN}$	Line Regulation	$(V_R + 1V) \le V_{IN} \le 6V$	—	0.05	0.35	%
$\Delta V_{OUT}/V_{OUT}$	Load Regulation	$I_L = 0.1 \text{mA}$ to $I_{OUT_{MAX}}$ Note 4	—	0.5	2	%
V <sub>IN</sub> – V <sub>OUT</sub>	Dropout Voltage	$I_{L} = 100\mu A$ $I_{L} = 50m A$ $I_{L} = 100m A$ $I_{L} = 150m A$ Note 5	 	2 80 160 240		mV
I <sub>IN</sub>	LDOs Supply Current	SHDN1, SHDN2=V <sub>IH</sub> , I <sub>L</sub> =0	_	120	160	μA
I <sub>INSD</sub>	LDOs Shutdown Supply Current	$\overline{\text{SHDN1}}$ , $\overline{\text{SHDN2}} = 0V$	_	0.05	0.5	μA
PSRR	Power Supply Rejection Ratio	F <sub>RE</sub> ≤ 1KHz	—	64	_	dB
IOUTSC	Output Short Circuit Current	V <sub>OUT</sub> = 0V	_	600	_	mA
$\Delta V_{OUT} / \Delta P_D$	Thermal Regulation	Notes 6, 7	—	0.04	_	V/W
twĸ	Wake Up Time (from Shutdown Mode)	$\label{eq:VIN} \begin{split} V_{IN} &= 5V\\ C_{IN} &= 1\mu\text{F},\ C_{OUT} = 4.7\mu\text{F}\\ I_L &= 30\text{mA},\ (\text{See Fig. 2}) \end{split}$	_	10	—	μsec
ts	Settling Time (from Shutdown Mode)	$\label{eq:VIN} \begin{split} V_{IN} &= 5V\\ C_{IN} &= 1\mu\text{F}, \ C_{OUT} = 4.7\mu\text{F}\\ I_L &= 30\text{mA}, \ (\text{See Fig. 2}) \end{split}$	_	40	—	μsec
T <sub>SD</sub>	Thermal Shutdown Die Temperature			160	_	°C
$\Delta T_{SD}$	Thermal Shutdown Hysteresis		—	10	—	°C
eN	Output Noise	$I_L = I_{OUTMAX}$ , F = 10kHz 470pF from Bypass to GND	—	600	—	nV/√Hz
SHDN Input	:					
V <sub>IH</sub>	SHDN Input High Threshold	V <sub>IN</sub> = 2.7V to 6.0V	65		_	%V <sub>IN</sub>
VIL	SHDN Input Low Threshold	V <sub>IN</sub> = 2.7V to 6.0V	_	_	15	%V <sub>IN</sub>
SELECT Inp	out			1	•	
V <sub>SELH</sub>	SELECT Input High Threshold	V <sub>IN</sub> = 2.7V to 6.0V	V <sub>IN</sub> - 0.2		_	V
V <sub>SELL</sub>	SELECT Input Low Threshold $V_{IN} = 2.7V$ to 6.0				0.2	V

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
RESET Ou	tput					
V <sub>DET</sub>	V <sub>DET</sub> Voltage Range	$T_A = 0^{\circ}C$ to +70°C	1.0		6.0	V
221		$T_A = -40^{\circ}C \text{ to } +125^{\circ}C$	1.2		6.0	
V <sub>TH</sub>	Reset Threshold	T <sub>A</sub> = +25°C	2.59	2.63	2.66	V
		$T_A = -40^{\circ}C \text{ to } +125^{\circ}C$	2.55		2.70	
IVDET	Reset Circuit Supply Current	RESET = Open	—	20	40	μΑ
	Reset Threshold Tempco		_	30	_	ppm/°C
	V <sub>DET</sub> to Reset Delay	$V_{DET} = V_{TH}$ to $(V_{TH} - 100mV)$	_	100	_	μsec
	Reset Active Timeout Period		140	300	560	msec
V <sub>OL</sub>	RESET Output Voltage Low	V <sub>DET</sub> = V <sub>TH</sub> min, I <sub>SINK</sub> = 1.2mA	_	_	0.3	V
		V <sub>DET</sub> = V <sub>TH</sub> min, I <sub>SINK</sub> = 3.2mA	_		0.4	
		$V_{DET}$ > 1.0V, $I_{SINK}$ = 50 $\mu$ A	—	_	0.3	
Voн	RESET Output Voltage High	V <sub>DET</sub> > V <sub>TH</sub> max, I <sub>SOURCE</sub> = 500µA	0.8 V <sub>DET</sub>	_	_	V

ELECTRICAL CHARACTERISTICS: VIN = VR + 1V, IL = 100µA, CL = 3.3µF, SHDN1 > VIH, SHDN2 > VIH, TA = 25°C, unless otherwise noted. Boldface type specifications apply for junction temperatures of - 40°C to +125°C.

 $V_{DET}$  >  $V_{TH}$  max,  $I_{SOURCE}$  = 800 $\mu$ A |  $V_{DET}$  - 1.5 **NOTES:** 1. The minimum  $V_{IN}$  has to meet two conditions:  $V_{IN} \ge 2.7V$  and  $V_{IN} \ge V_R + V_{DROPOUT}$ .

2. V<sub>R</sub> is the regulator output voltage setting. For example: V<sub>R</sub> = 2.5V, 2.8V, 3.0V.

3. TCV<sub>OUT</sub> =  $(V_{OUT_{MAX}} - V_{OUT_{MIN}}) \times 10^6$ 

V<sub>OUT</sub> x ΔT

4. Regulation is measured at a constant junction temperature using low duty cycle pulse testing. Load regulation is tested over a load range from 0.1mA to the maximum specified output current. Changes in output voltage due to heating effects are covered by the thermal regulation specification.

5. Dropout voltage is defined as the input to output differential at which the output voltage drops 2% below its nominal value at a 1V differential. 6. Thermal Regulation is defined as the change in output voltage at a time, t, after a change in power dissipation is applied, excluding load or line regulation effects. Specifications are for a current pulse equal to  $I_{LMAX}$  at  $V_{IN}$  = 6V for t = 10msec.

7. The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction-to-air (i.e. T<sub>A</sub>, T<sub>J</sub>, θ<sub>JA</sub>). Exceeding the maximum allowable power dissipation causes the device to initiate thermal shutdown. Please see Thermal Considerations section of this data sheet for more details.

#### **PIN DESCRIPTION**

Pin No. (10-Pin MSOP)	Symbol	Description
1	V <sub>DET</sub>	Detected input voltage. V <sub>DET</sub> and V <sub>IN</sub> can be connected together.
2	V <sub>IN</sub>	Power supply input.
3	GND	Ground terminal.
4	SELECT	Tri-state input for setting $V_{OUT1}$ and $V_{OUT2}$ . SELECT = GND for $V_{OUT1} = V_{OUT2} = 2.5V$ , SELECT = $V_{IN}$ for $V_{OUT1} = V_{OUT2} = 3.0V$ and SELECT = No connect for $V_{OUT1} = V_{OUT2} = 2.8V$ .
5	SHDN1	Shutdown control input for V <sub>OUT1</sub> . Regulator 1 is fully enabled when a logic high is applied to this input. Regulator 1 enters shutdown when a logic low is applied to this input. During shutdown, regulator output voltage falls to zero, RESET output remains valid.
6	SHDN2	Shutdown control input for V <sub>OUT2</sub> . Regulator 2 is fully enabled when a logic high is applied to this input. Regulator 2 enters shutdown when a logic low is applied to this input. During shutdown, regulator output voltage falls to zero, RESET output remains valid.
7	Bypass	Reference bypass input. Connecting a 470pF to this input further reduces output noise.
8	V <sub>OUT1</sub>	Regulated voltage output 1.
9	V <sub>OUT2</sub>	Regulated voltage output 2.
10	RESET	RESET Output. RESET = Low when $V_{DET}$ is below the Reset Threshold Voltage.
		RESET = High when V <sub>DET</sub> is above the Reset Threshold Voltage.

## **DETAILED DESCRIPTION**

The TC1305 is a precision fixed output voltage regulator that contains two fully independent 150mA regulator outputs. The device features seperate shutdown modes for low-power operation, and a common bypass pin that can be used to further reduce output noise. The SelectMode<sup>TM</sup> allows the user to select V<sub>OUT1</sub> and V<sub>OUT2</sub> from three different values (2.5V, 2.8V, 3.0V), therefore providing high design flexibility. The CMOS construction of the TC1305 results to a very low supply current, which does not increase with load changes. In addition, V<sub>OUT</sub> remains stable and within regulation at very low load currents.

The TC1305 also features an integrated microprocessor supervisor that monitors power-up, power-down, and brown-out conditions. The active low RESET signal is asserted when the detected voltage  $V_{DET}$  falls below the reset voltage threshold (2.63V). The RESET output remains low for 300msec (typical) after  $V_{DET}$  rises above the reset threshold. The RESET output of the TC1305 is guaranteed valid down to  $V_{DET}$ =1V and is optimized to reject fast transient glitches on the moinitored power supply line.

## **APPLICATION INFORMATION**

#### Input and Output Capacitor

The TC1305 is stable with a wide range of capacitor values and types. A capacitor with a minimum value of  $1\mu$ F from V<sub>OUT</sub> to Ground is required. The output capacitor should have an effective series resistance (ESR) of  $5\Omega$  or less. A  $1\mu$ F capacitor should be connected from the V<sub>IN</sub> to GND if there is more than 10 inches of wire between the regulator and the AC filter capacitor, or if a battery is used as the power source. Aluminum electrolytic or tantalum capacitor types can be used. (Since many aluminum electrolytic capacitors freeze at approximately –  $30^{\circ}$ C, solid tantalums are recommended for applications operating between  $-20^{\circ}$ C). When operating from sources other than batteries, supply-noise rejection and transient response can be improved by increasing the value of the input and output capacitors and employing passive filtering techniques.

#### **Bypass Capacitor**

A 470pF capacitor connected from the Bypass input to ground reduces noise present on the internal reference, which in turn significantly reduces output noise. If output noise is not a concern, this input may be left unconnected.

Larger capacitor values may be used, but result in a longer time period to rated output voltage when power is initially applied.

#### **Shutdown Mode**

Applying a logic high to each of the shutdown pins turns on the corresponding output. Each regulator enters shutdown mode when a logic low is applied in the corresponding input. During shutdown mode, output voltage falls to zero, and regulator supply current is reduced to  $0.5\mu$ A (max). If shutdown mode is not necessary, the pins should be connected to V<sub>IN</sub>.

#### SelectMode<sup>™</sup>

The SelectMode<sup>TM</sup> is a tri-state input that allows the user to select  $V_{OUT1}$  and  $V_{OUT2}$  from three different values. By connecting the SELECT pin to GND, both output voltages ( $V_{OUT1}$ ,  $V_{OUT2}$ ) supply 2.5V. Connecting the SELECT pin to  $V_{IN}$  results to both output channels supplying a fixed 3.0V output. Last but not least, leaving the SELECT pin floating sets both voltages to 2.8V. This output voltage functionality provides high design flexibility and minimizes costs associated with inventory, time-to-market and new devices' qualifications.

#### **RESET** Output

The microprocessor supervisor of the TC1305 provides accurate supply voltage monitoring and reset timing during power-up, power-down and brown-out conditions. The RESET output is valid to  $V_{DET}$ =1.0V (below this point it becomes an open circuit and does not sink current) and is able to reject negative going transients (glitches) on the power supply line. Transient immunity can further be improved by adding a capacitor close to the V<sub>DET</sub> pin of the TC1305.

### Turn On Response

The turn on response is defined as two separate response categories, Wake Up Time ( $t_{WK}$ ) and Settling Time ( $t_s$ ).

The TC1305 has a fast Wake Up Time (10 $\mu$ sec typical) when released from shutdown. See Figure 2 for the **Wake Up Time** designated as  $t_{WK}$ . The **Wake Up Time** is defined as the time it takes for the output to rise to 2% of the V<sub>OUT</sub> value after being released from shutdown.

The total turn on response is defined as the **Settling Time (t<sub>S</sub>)**, see Figure 2. **Settling Time** (inclusive with  $t_{WK}$ ) is defined as the condition when the output is within 2% of its fully enabled value (40µsec typical) when released from shutdown. The settling time of the output voltage is dependent on load conditions and output capacitance on V<sub>OUT</sub> (RC response).

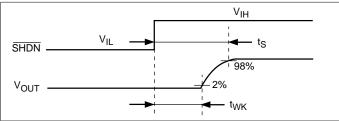


Figure 2: Wake Up Response Time

#### **Thermal Considerations**

#### **Thermal Shutdown**

Integrated thermal protection circuitry shuts the regulator off when die temperature exceeds 160°C. The regulator remains off until the die temperature drops to approximately 150°C.

#### **Power Dissipation**

The amount of power the regulator dissipates is primarily a function of input and output voltage, and output current. The following equation is used to calculate worst case *actual* power dissipation:

$$\begin{split} P_D &\approx (V_{\text{IN}_{MAX}} - V_{\text{OUT}_{MIN}}) I_{\text{LOAD}_{MAX}} \\ \text{Where:} \quad & P_D = \text{worst case actual power dissipation} \\ & V_{\text{IN}_{MAX}} = \text{maximum voltage on } V_{\text{IN}} \\ & V_{\text{OUT}_{MIN}} = \text{minimum regulator output voltage} \\ & I_{\text{LOAD}_{MAX}} = \text{maximum output (load) current} \end{split}$$

Equation 1.

The maximum *allowable* power dissipation (Equation 2) is a function of the maximum ambient temperature ( $T_{AMAX}$ ), the maximum allowable die temperature (125°C), and the thermal resistance from junction-to-air ( $\theta_{JA}$ ). The MSOP-10 package has a  $\theta_{JA}$  of approximately **113°C/W** when mounted

on a single layer FR4 dielectric copper clad PC board.

$$\mathsf{P}_{\mathsf{DMAX}} = (\underbrace{\mathsf{T}_{\mathsf{JMAX}} - \mathsf{T}_{\mathsf{AMAX}}}_{\theta_{\mathsf{JA}}})$$

Where all terms are previously defined.

Equation 2.

Equation 1 can be used in conjunction with Equation 2 to ensure regulator thermal operation is within limits. For example:

FIND:

1) Actual power dissipation:

 $\begin{array}{l} \mathsf{P}_{\mathsf{D}} &\approx [(\mathsf{Vin}_{\mathsf{MAX}} - \mathsf{Vout1}_{\mathsf{MIN}}) \ x \ \mathsf{ILOAD1}_{\mathsf{MAX}} \\ &+ [(\mathsf{Vin}_{\mathsf{MAX}} - \mathsf{Vout2}_{\mathsf{MIN}}) \ x \ \mathsf{ILOAD2}_{\mathsf{MAX}} \\ &\quad [(3.8 \ x \ 1.05) - (3.0 \ x \ .975)] \ x \ 120 \ x \ 10^{-3} \\ &+ [(3.8 \ x \ 1.05) - (3.0 \ x \ .975)] \ x \ 120 \ x \ 10^{-3} \end{array}$ 

2) Maximum allowable power dissipation:

$$P_{D} \approx \frac{(T_{J_{MAX}} - T_{A_{MAX}})}{\theta_{JA}}$$
$$= \frac{(125 - 55)}{113}$$
$$= 620 \text{mW}$$

In this example, the TC1305 dissipates a maximum of only 256mW; far below the allowable limit of 620mW. In a similar manner, Equation 1 and Equation 2 can be used to calculate maximum current and/or input voltage limits. For example, the maximum allowable  $V_{IN}$  is found by substituting the maximum allowable power dissipation of 620mW into Equation 1, from which  $V_{INMAX} = 5.3V$ .

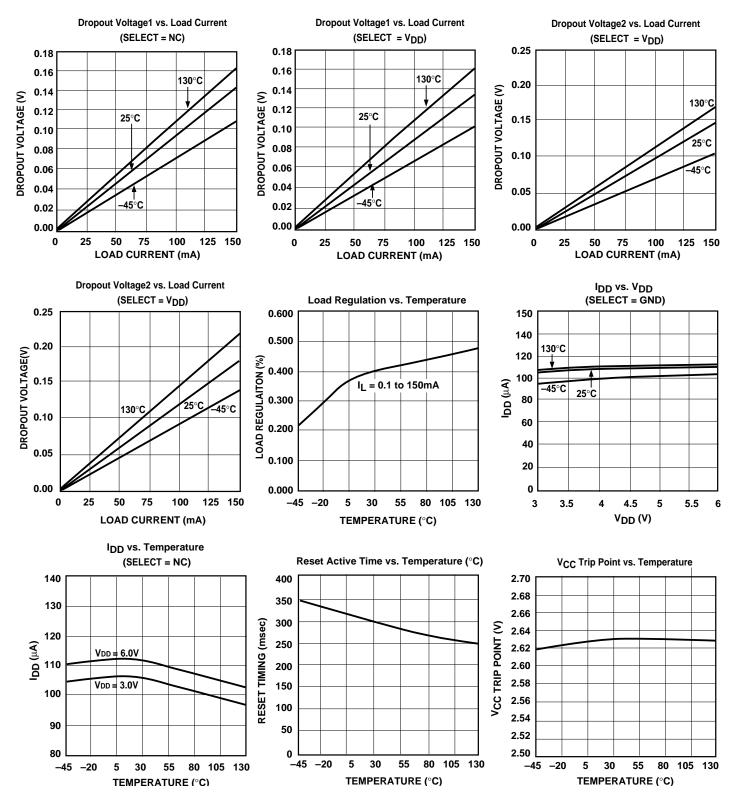
#### Layout Considerations

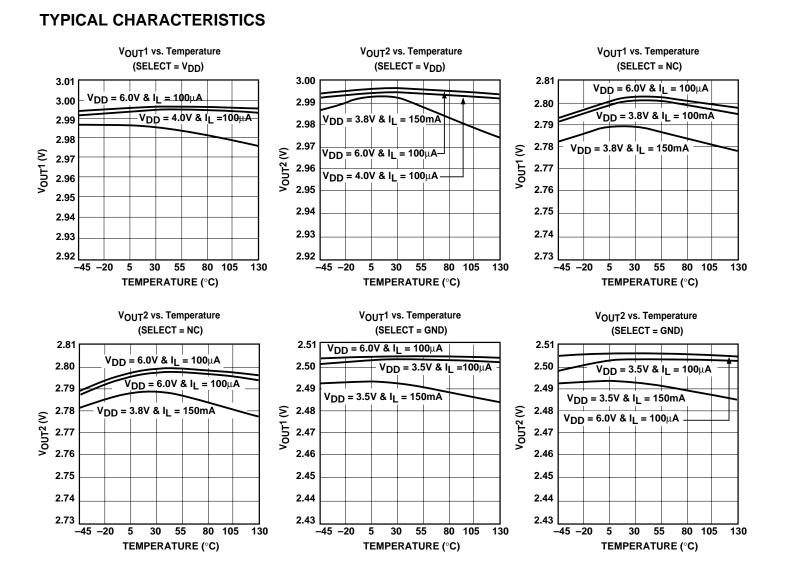
The primary path of heat conduction out of the package is via the package leads. Therefore, layouts having a ground plane, wide traces at the pads, and wide power supply bus lines combine to lower  $\theta_{JA}$  and, therefore, increase the maximum allowable power dissipation limit.

# Dual 150mA CMOS LDO With Select Mode<sup>™</sup>, Shutdown an<u>d Inde</u>pendent RESET Output

# TC1305

# **TYPICAL CHARACTERISTICS**

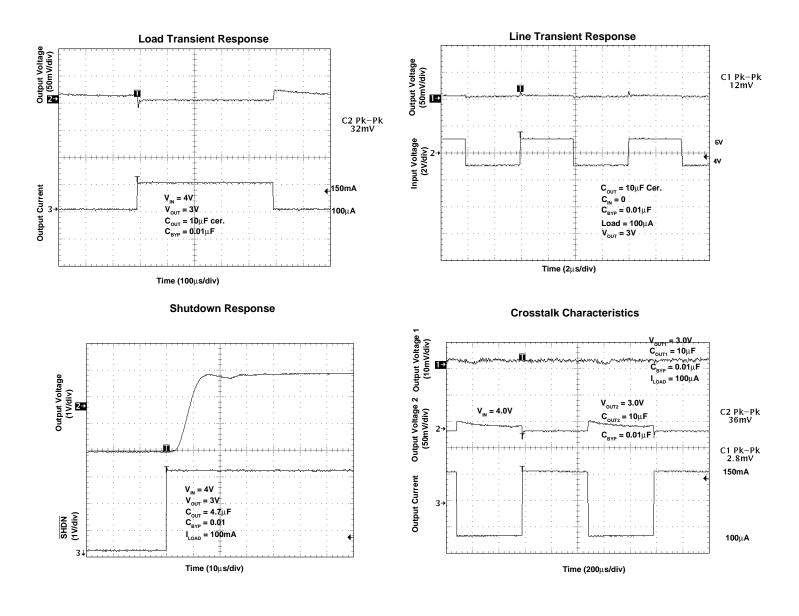




# Dual 150mA CMOS LDO With Select Mode™, Shutdown an<u>d Indep</u>endent RESET Output

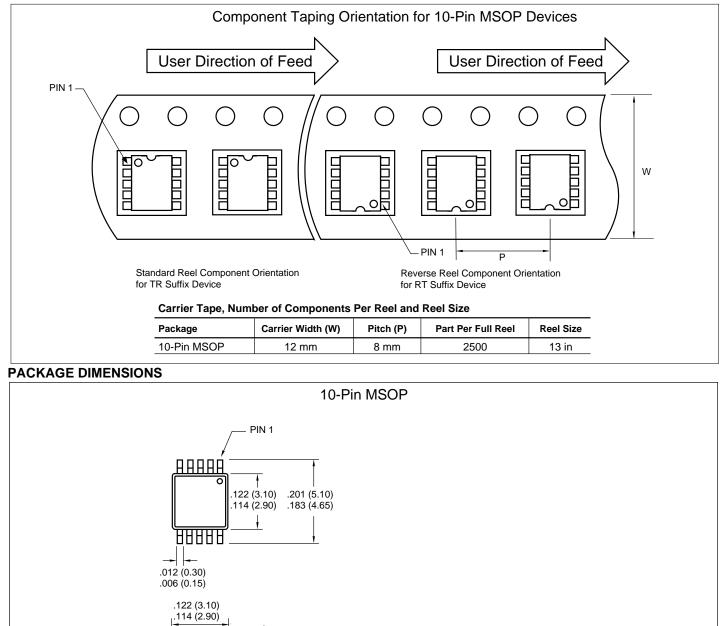
# TC1305

# **TYPICAL CHARACTERISTICS**



# Dual 150mA CMOS LDO With Select Mode<sup>™</sup>, Shutdown and Independent RESET Output

#### TAPE AND REEL DIAGRAMS



Dimensions: inches (mm)

.009 (0.23)

.005 (0.13)

6° MAX

.028 (0.70) .016 (0.40)

.043 (1.10)

MÀX.

.006 (0.15)

.002 (0.05)

чннны

.020 (0.50)



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